

ABSTRACT

A system (10) is disclosed having a circuit portion (18,26,36) containing more than electrical conductors and a wirebonded assemblage (12,14,16) overlying the circuit portion (18,26,36). The wirebonded assemblage (12,14,16) comprises a plurality of wirebonded
5 wires ((50,52),(60,64),(66,68)), each of the plurality of wirebonded wires being electrically coupled. The wirebonded assemblage (12,14,16) provides electrical shielding for the circuit portion (18,26,36). In one embodiment, the wirebonded assemblage provides for heat spreading.